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OKing
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

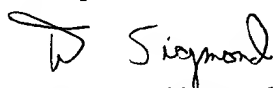
Applicant: Charles W.C. Lin
Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA
Serial No.: Unknown Filed: Herewith
Examiner: Unknown Group Art Unit: Unknown
Atty. Docket No.: P002-2

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

**SUBMISSION OF PROPOSED DRAWING AMENDMENT
FOR APPROVAL BY EXAMINER**

Attached please find a copy of the original Figures 1A and 1B with red ink markings showing the proposed changes to the drawings in the above-identified application in accordance with 37 C.F.R. § 1.123. The Examiner's approval for these changes is requested.

Respectfully submitted,



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T00T50-12325860

FIG. 1A

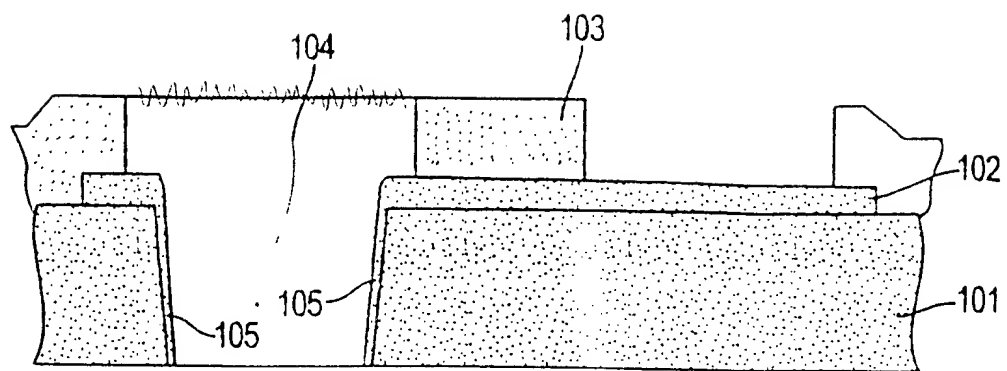


FIG. 1B

